

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







DISCRETE SEMICONDUCTORS

DATA SHEET



BYD17 series General purpose controlled avalanche rectifiers

Product specification Supersedes data of 1999 Nov 11 2001 Oct 26





General purpose controlled avalanche rectifiers

BYD17 series

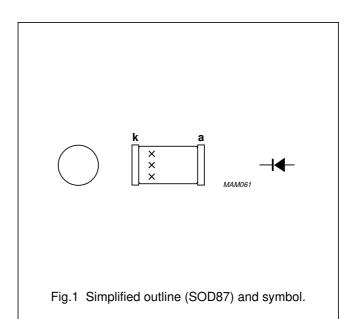
FEATURES

- · Glass passivated
- High maximum operating temperature
- · Low leakage current
- · Excellent stability
- · Guaranteed avalanche energy absorption capability
- Shipped in 8 mm embossed tape
- Smallest surface mount rectifier outline.

DESCRIPTION

Cavity free cylindrical glass package through Implotec $^{\text{TM}(1)}$ technology.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		_	800	V
	BYD17M		_	1000	V
V _{RWM}	crest working reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		_	800	V
	BYD17M		_	1000	V
V _R	continuous reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		_	800	V
	BYD17M		_	1000	V

⁽¹⁾ Implotec is a trademark of Philips.

General purpose controlled avalanche rectifiers

BYD17 series

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{F(AV)}	average forward current	T _{tp} = 105 °C; averaged over any 20 ms period; see Figs 2 and 4	_	1.5	A
		T _{amb} = 65 °C; PCB mounting (see Fig.9); averaged over any 20 ms period; see Figs 3 and 4	-	0.6	A
I _{FSM}	non-repetitive peak forward current	t = 10 ms half sinewave; $T_j = T_{j \text{ max}}$ prior to surge; $V_R = V_{RRMmax}$	_	20	A
E _{RSM}	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j \text{ max}}$ prior to surge; inductive load switched off	_	7	mJ
T _{stg}	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.5	-65	+175	°C

ELECTRICAL CHARACTERISTICS

 $T_i = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	$I_F = 1 A; T_j = T_{j \text{ max}}; \text{see Fig.6}$	_	_	0.93	V
		I _F = 1 A; see Fig.6	_	_	1.05	V
V _{(BR)R}	reverse avalanche breakdown voltage	I _R = 0.1 mA				
	BYD17D		225	_	_	V
	BYD17G		450	_	_	V
	BYD17J		650	_	_	V
	BYD17K		900	_	_	V
	BYD17M		1100	_	_	V
I _R	reverse current	V _R = V _{RRMmax} ; see Fig.7	_	_	1	μΑ
		V _R = V _{RRMmax} ; T _j = 165 °C; see Fig.7	-	_	100	μΑ
t _{rr}	reverse recovery time	when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.10	_	3	_	μs
C _d	diode capacitance	V _R = 0 V; f = 1 MHz; see Fig.8	_	21	_	рF

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point		30	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	150	K/W

Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper \geq 40 μ m, see Fig.9. For more information please refer to the "General Part of associated Handbook".

General purpose controlled avalanche rectifiers

BYD17 series

GRAPHICAL DATA

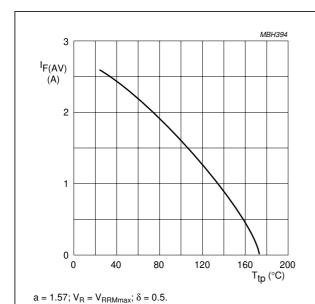


Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

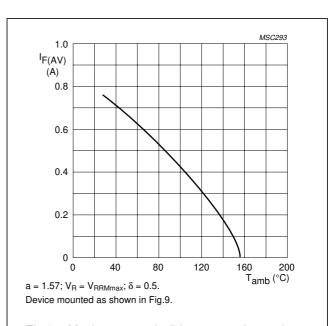


Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

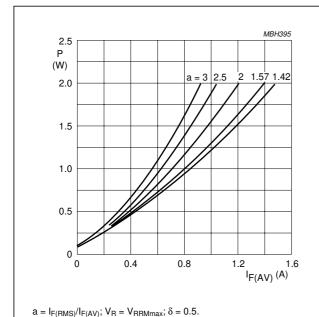


Fig.4 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

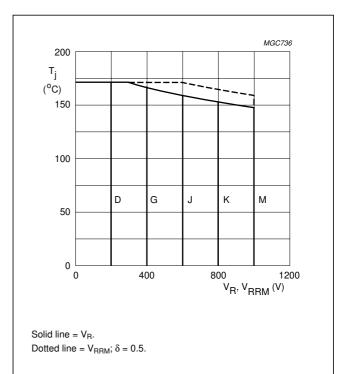
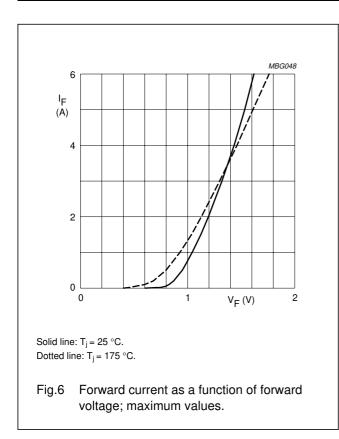
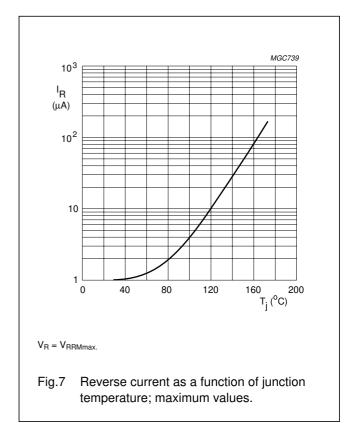


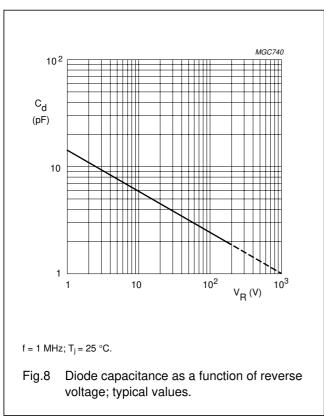
Fig.5 Maximum permissible junction temperature as a function of reverse voltage.

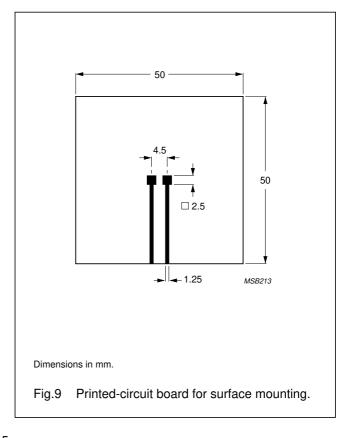
General purpose controlled avalanche rectifiers

BYD17 series



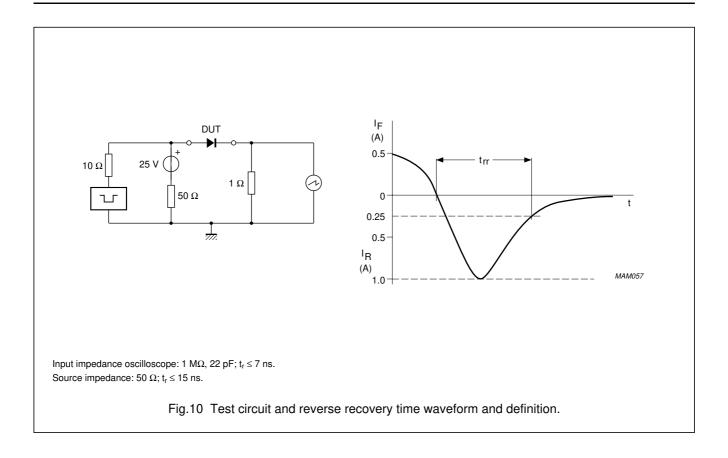






General purpose controlled avalanche rectifiers

BYD17 series



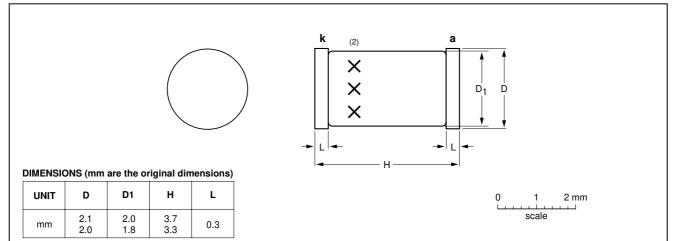
General purpose controlled avalanche rectifiers

BYD17 series

PACKAGE OUTLINE

Hermetically sealed glass surface mounted package; Implotec $^{\mathsf{TM}(1)}$ technology; 2 connectors

SOD87



Notes

- 1. Implotec is a trademark of Philips.
- 2. The marking indicates the cathode.

OUTLINE		REFERENCES			EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOD87	100H03					-99-03-31 99-06-04	

General purpose controlled avalanche rectifiers

BYD17 series

DATA SHEET STATUS

DATA SHEET STATUS(1)	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

DISCLAIMERS

Life support applications — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no licence or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

General purpose controlled avalanche rectifiers

BYD17 series

NOTES

General purpose controlled avalanche rectifiers

BYD17 series

NOTES

General purpose controlled avalanche rectifiers

BYD17 series

NOTES

Philips Semiconductors – a worldwide company

Contact information

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

© Koninklijke Philips Electronics N.V. 2001

SCA73

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

613510/04/pp12

Date of release: 2001 Oct 26

Document order number: 9397 750 08864

Let's make things better.

Philips Semiconductors



